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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	163840
Number of I/O	316
Number of Gates	569952
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	432-LBGA Exposed Pad, Metal
Supplier Device Package	432-MBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv400e-7bg432i

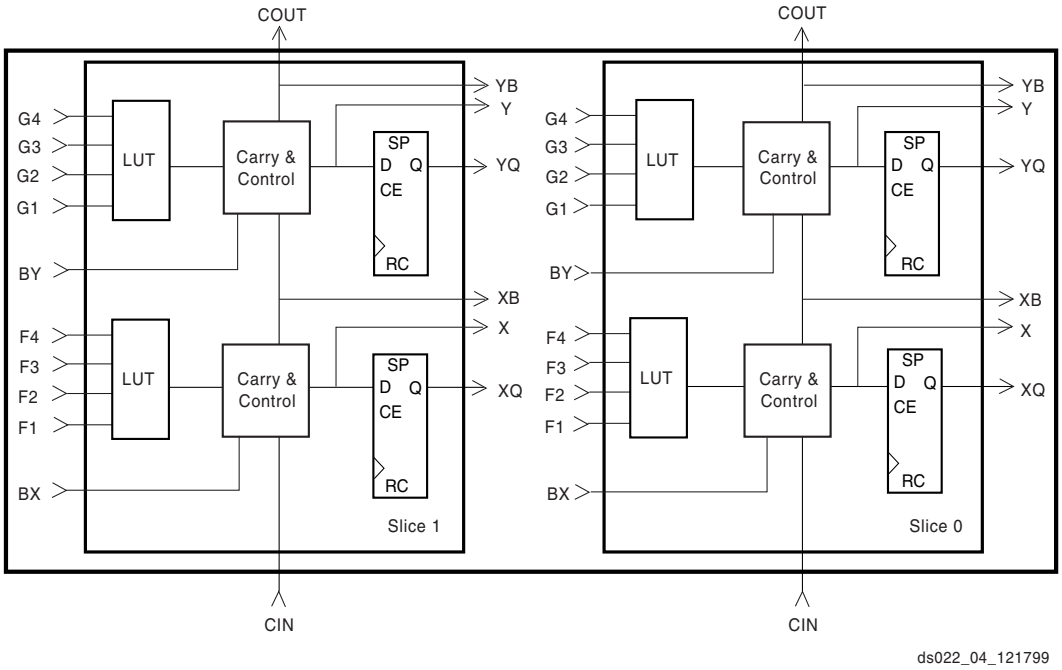

Figure 4: **2-Slice Virtex-E CLB**

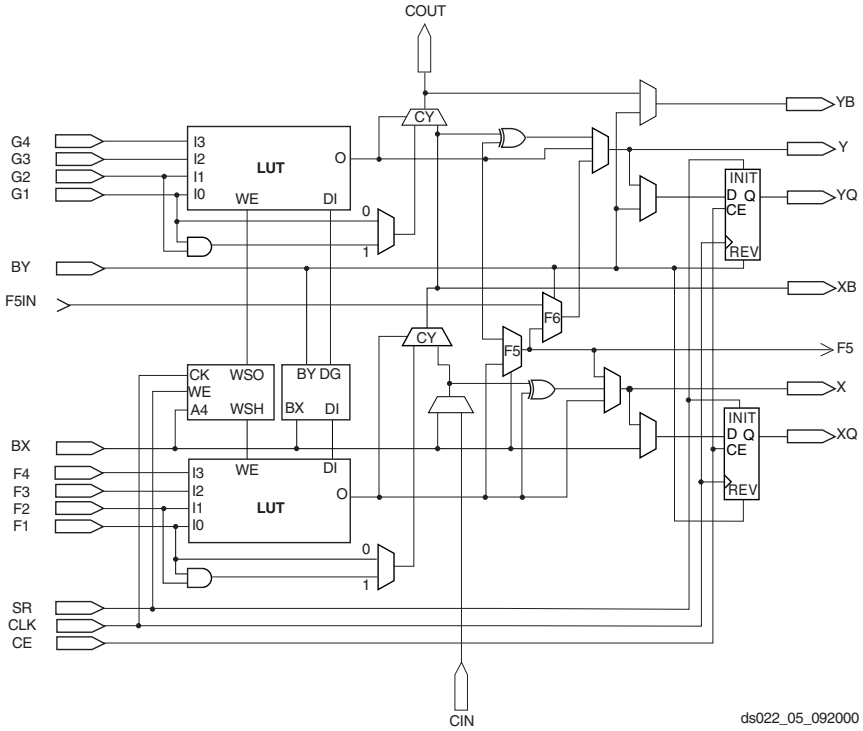

Figure 5: **Detailed View of Virtex-E Slice**

Storage Elements

The storage elements in the Virtex-E slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D inputs can be driven either by the function generators within the slice or directly from slice inputs, bypassing the function generators.

In addition to Clock and Clock Enable signals, each Slice has synchronous set and reset signals (SR and BY). SR

For in-circuit debugging, an optional download and readback cable is available. This cable connects the FPGA in the target system to a PC or workstation. After downloading the design into the FPGA, the designer can single-step the logic, readback the contents of the flip-flops, and so observe the internal logic state. Simple modifications can be downloaded into the system in a matter of minutes.

Configuration

Virtex-E devices are configured by loading configuration data into the internal configuration memory. Note that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Some of the pins used for configuration are dedicated pins, while others can be re-used as general purpose inputs and outputs once configuration is complete.

The following are dedicated pins:

- Mode pins (M2, M1, M0)
- Configuration clock pin (CCLK)
- $\overline{\text{PROGRAM}}$ pin
- DONE pin
- Boundary Scan pins (TDI, TDO, TMS, TCK)

Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or can be generated externally and provided to the FPGA as an input. The $\overline{\text{PROGRAM}}$ pin must be pulled High prior to reconfiguration.

Note that some configuration pins can act as outputs. For correct operation, these pins require a V_{CCO} of 3.3 V or 2.5 V. At 3.3 V the pins operate as LVTTL, and at 2.5 V they operate as LVCMOS. All affected pins fall in banks 2 or 3. The configuration pins needed for SelectMap (CS, Write) are located in bank 1.

Configuration Modes

Virtex-E supports the following four configuration modes.

- Slave-serial mode
- Master-serial mode
- SelectMAP mode
- Boundary Scan mode (JTAG)

The Configuration mode pins (M2, M1, M0) select among these configuration modes with the option in each case of having the IOB pins either pulled up or left floating prior to configuration. The selection codes are listed in Table 8.

Configuration through the Boundary Scan port is always available, independent of the mode selection. Selecting the Boundary Scan mode simply turns off the other modes. The three mode pins have internal pull-up resistors, and default to a logic High if left unconnected. However, it is recommended to drive the configuration mode pins externally.

Table 8: **Configuration Codes**

Configuration Mode	M2[1]	M1	M0	CCLK Direction	Data Width	Serial D_{out}	Configuration Pull-ups[1]
Master-serial mode	0	0	0	Out	1	Yes	No
Boundary Scan mode	1	0	1	N/A	1	No	No
SelectMAP mode	1	1	0	In	8	No	No
Slave-serial mode	1	1	1	In	1	Yes	No
Master-serial mode	1	0	0	Out	1	Yes	Yes
Boundary Scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Notes:
1. M2 is sampled continuously from power up until the end of the configuration. Toggling M2 while INIT is being held externally Low can cause the configuration pull-up settings to change.

3. At the rising edge of CCLK: If BUSY is Low, the data is accepted on this clock. If BUSY is High (from a previous write), the data is not accepted. Acceptance instead occurs on the first clock after BUSY goes Low, and the data must be held until this has happened.
4. Repeat steps 2 and 3 until all the data has been sent.
5. De-assert $\overline{CS}$ and $\overline{WRITE}$.

Table 11: **SelectMAP Write Timing Characteristics**

	Description		Symbol		Units
CCLK	D_{0-7} Setup/Hold	1/2	T_{SMDCC}/T_{SMCCD}	5.0 / 1.7	ns, min
	$\overline{CS}$ Setup/Hold	3/4	T_{SMCSCC}/T_{SMCCCS}	7.0 / 1.7	ns, min
	$\overline{WRITE}$ Setup/Hold	5/6	T_{SMCCW}/T_{SMWCC}	7.0 / 1.7	ns, min
	BUSY Propagation Delay	7	T_{SMCKBY}	12.0	ns, max
	Maximum Frequency		F_{CC}	66	MHz, max
	Maximum Frequency with no handshake		F_{CCNH}	50	MHz, max

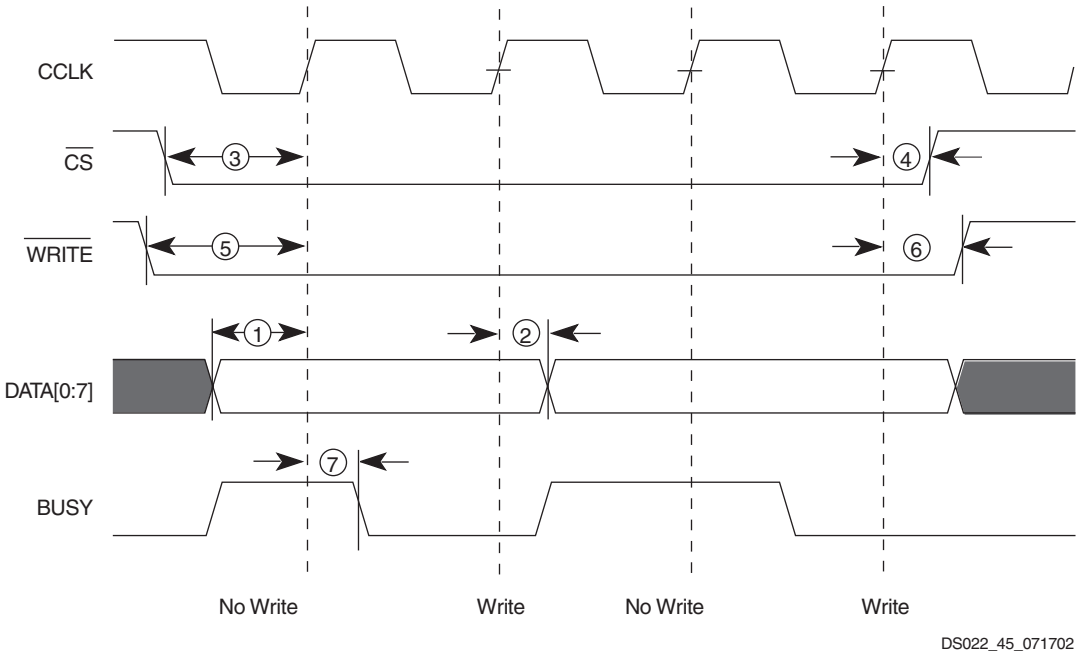

Figure 17: **Write Operations**

A flowchart for the write operation is shown in Figure 18. Note that if CCLK is slower than f_{CCNH}, the FPGA never asserts BUSY, In this case, the above handshake is unnecessary, and data can simply be entered into the FPGA every CCLK cycle.

Abort

During a given assertion of $\overline{CS}$, the user cannot switch from a write to a read, or vice-versa. This action causes the current packet command to be aborted. The device remains BUSY until the aborted operation has completed. Following an abort, data is assumed to be unaligned to word boundaries, and the FPGA requires a new synchronization word prior to accepting any new packets.

To initiate an abort during a write operation, de-assert $\overline{WRITE}$. At the rising edge of CCLK, an abort is initiated, as shown in Figure 19.

standard requires a Differential Amplifier input buffer and a Push-Pull output buffer.

SSTL3 — Stub Series Terminated Logic for 3.3V

The Stub Series Terminated Logic for 3.3V, or SSTL3 standard is a general purpose 3.3V memory bus standard also sponsored by Hitachi and IBM (JESD8-8). This standard has two classes, I and II. SelectI/O devices support both classes for the SSTL3 standard. This standard requires a Differential Amplifier input buffer and an Push-Pull output buffer.

SSTL2 — Stub Series Terminated Logic for 2.5V

The Stub Series Terminated Logic for 2.5V, or SSTL2 standard is a general purpose 2.5V memory bus standard sponsored by Hitachi and IBM (JESD8-9). This standard has two classes, I and II. SelectI/O devices support both classes for the SSTL2 standard. This standard requires a Differential Amplifier input buffer and an Push-Pull output buffer.

CTT — Center Tap Terminated

The Center Tap Terminated, or CTT standard is a 3.3V memory bus standard sponsored by Fujitsu (JESD8-4). This standard requires a Differential Amplifier input buffer and a Push-Pull output buffer.

AGP-2X — Advanced Graphics Port

The Intel AGP standard is a 3.3V Advanced Graphics Port-2X bus standard used with the Pentium II processor for graphics applications. This standard requires a Push-Pull output buffer and a Differential Amplifier input buffer.

LVDS — Low Voltage Differential Signal

LVDS is a differential I/O standard. It requires that one data bit is carried through two signal lines. As with all differential signaling standards, LVDS has an inherent noise immunity over single-ended I/O standards. The voltage swing between two signal lines is approximately 350mV. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required. LVDS requires the use of two pins per input or output. LVDS requires external resistor termination.

BLVDS — Bus LVDS

This standard allows for bidirectional LVDS communication between two or more devices. The external resistor termination is different than the one for standard LVDS.

LVPECL — Low Voltage Positive Emitter Coupled Logic

LVPECL is another differential I/O standard. It requires two signal lines for transmitting one data bit. This standard specifies two pins per input or output. The voltage swing between these two signal lines is approximately 850 mV. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required. The LVPECL standard requires external resistor termination.

Library Symbols

The Xilinx library includes an extensive list of symbols designed to provide support for the variety of SelectI/O features. Most of these symbols represent variations of the five generic SelectI/O symbols.

- IBUF (input buffer)
- IBUFG (global clock input buffer)
- OBUF (output buffer)
- OBUFT (3-state output buffer)
- IOBUF (input/output buffer)

IBUF

Signals used as inputs to the Virtex-E device must source an input buffer (IBUF) via an external input port. The generic Virtex-E IBUF symbol appears in Figure 37. The extension

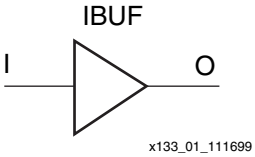

Figure 37: **Input Buffer (IBUF) Symbols**

to the base name defines which I/O standard the IBUF uses. The assumed standard is LVTTL when the generic IBUF has no specified extension.

The following list details the variations of the IBUF symbol:

- IBUF
- IBUF_LVCMOS2
- IBUF_PCI33_3
- IBUF_PCI66_3
- IBUF_GTL
- IBUF_GTLP
- IBUF_HSTL_I
- IBUF_HSTL_III
- IBUF_HSTL_IV
- IBUF_SSTL3_I
- IBUF_SSTL3_II
- IBUF_SSTL2_I
- IBUF_SSTL2_II
- IBUF_CTT
- IBUF_AGP
- IBUF_LVCMOS18
- IBUF_LVDS
- IBUF_LVPECL

When the IBUF symbol supports an I/O standard that requires a V_{REF}, the IBUF automatically configures as a differential amplifier input buffer. The V_{REF} voltage must be supplied on the V_{REF} pins. In the case of LVDS, LVPECL, and BLVDS, V_{REF} is not required.

SSTL3_I

A sample circuit illustrating a valid termination technique for SSTL3_I appears in Figure 49. DC voltage specifications appear in Table 28.

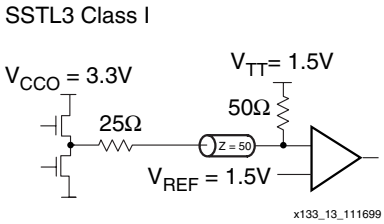

Figure 49: **Terminated SSTL3 Class I**

Table 28: **SSTL3_I Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	**3.0**	**3.3**	**3.6**
V_{REF} = 0.45 × V_{CCO}	1.3	1.5	1.7
V_{TT} = V_{REF}	1.3	1.5	1.7
V_{IH} = V_{REF} + 0.2	1.5	1.7	3.9(1)
V_{IL} = V_{REF} – 0.2	–0.3(2)	1.3	1.5
V_{OH} = V_{REF} + 0.6	1.9	-	-
V_{OL} = V_{REF} – 0.6	-	-	1.1
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	8	-	-

Notes:
1. V_{IH} maximum is V_{CCO} + 0.3
2. V_{IL} minimum does not conform to the formula

SSTL3_II

A sample circuit illustrating a valid termination technique for SSTL3_II appears in Figure 50. DC voltage specifications appear in Table 29.

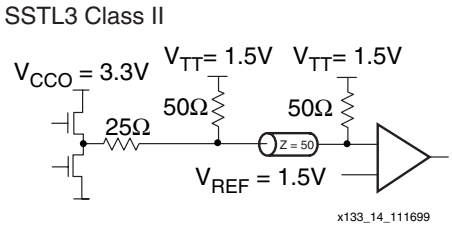

Figure 50: **Terminated SSTL3 Class II**

Table 29: **SSTL3_II Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF} = 0.45 × V_{CCO}	1.3	1.5	1.7
V_{TT} = V_{REF}	1.3	1.5	1.7
V_{IH} = V_{REF} + 0.2	1.5	1.7	3.9(1)
V_{IL}= V_{REF} – 0.2	–0.3(2)	1.3	1.5
V_{OH} = V_{REF} + 0.8	2.1	-	-
V_{OL}= V_{REF} – 0.8	-	-	0.9
I_{OH} at V_{OH} (mA)	–16	-	-
I_{OL}at V_{OL} (mA)	16	-	-

Notes:
1. V_{IH} maximum is V_{CCO} + 0.3
2. V_{IL} minimum does not conform to the formula

SSTL2_I

A sample circuit illustrating a valid termination technique for SSTL2_I appears in Figure 51. DC voltage specifications appear in Table 30.

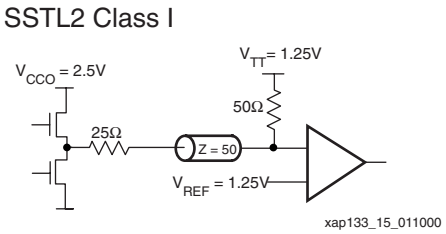

Figure 51: **Terminated SSTL2 Class I**

Table 30: **SSTL2_I Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
V_{REF} = 0.5 × V_{CCO}	1.15	1.25	1.35
V_{TT} = V_{REF} + N(1)	1.11	1.25	1.39
V_{IH} = V_{REF} + 0.18	1.33	1.43	3.0(2)
V_{IL} = V_{REF} – 0.18	–0.3(3)	1.07	1.17
V_{OH} = V_{REF} + 0.61	1.76	-	-
V_{OL}= V_{REF} – 0.61	-	-	0.74
I_{OH} at V_{OH} (mA)	–7.6	-	-
I_{OL}at V_{OL} (mA)	7.6	-	-

Notes:
1. N must be greater than or equal to -0.04 and less than or equal to 0.04.
2. V_{IH} maximum is V_{CCO} + 0.3.
3. V_{IL} minimum does not conform to the formula.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
  Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
  Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
  DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
  Pinout Tables (Module 4)

Calculation of T_{ioop} as a Function of Capacitance

T_{ioop} is the propagation delay from the O Input of the IOB to the pad. The values for T_{ioop} are based on the standard capacitive load (C_{sl}) for each I/O standard as listed in Table 3.

Table 3: **Constants for Use in Calculation of T_{ioop}**

Standard	Csl (pF)	fl (ns/pF)
LVTTL Fast Slew Rate, 2mA drive	35	0.41
LVTTL Fast Slew Rate, 4mA drive	35	0.20
LVTTL Fast Slew Rate, 6mA drive	35	0.13
LVTTL Fast Slew Rate, 8mA drive	35	0.079
LVTTL Fast Slew Rate, 12mA drive	35	0.044
LVTTL Fast Slew Rate, 16mA drive	35	0.043
LVTTL Fast Slew Rate, 24mA drive	35	0.033
LVTTL Slow Slew Rate, 2mA drive	35	0.41
LVTTL Slow Slew Rate, 4mA drive	35	0.20
LVTTL Slow Slew Rate, 6mA drive	35	0.10
LVTTL Slow Slew Rate, 8mA drive	35	0.086
LVTTL Slow Slew Rate, 12mA drive	35	0.058
LVTTL Slow Slew Rate, 16mA drive	35	0.050
LVTTL Slow Slew Rate, 24mA drive	35	0.048
LVCMOS2	35	0.041
LVCMOS18	35	0.050
PCI 33 MHZ 3.3 V	10	0.050
PCI 66 MHz 3.3 V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:
1. I/O parameter measurements are made with the capacitance values shown above. See the application examples (in Module 2 of this data sheet) for appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

For other capacitive loads, use the formulas below to calculate the corresponding T_{ioop}:

$$T_{ioop} = T_{ioop} + T_{opadjust} + (C_{load} - C_{sl}) * fl$$

where:

$T_{opadjust}$ is reported above in the Output Delay Adjustment section.

C_{load} is the capacitive load for the design.

Table 4: **Delay Measurement Methodology**

Standard	V_L[1]	V_H[1]	Meas. Point	V_{REF} (Typ)[2]
LVTTL	0	3	1.4	-
LVCMOS2	0	2.5	1.125	-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	V_{REF} –0.2	V_{REF} +0.2	V_{REF}	0.80
GTL+	V_{REF} –0.2	V_{REF} +0.2	V_{REF}	1.0
HSTL Class I	V_{REF} –0.5	V_{REF} +0.5	V_{REF}	0.75
HSTL Class III	V_{REF} –0.5	V_{REF} +0.5	V_{REF}	0.90
HSTL Class IV	V_{REF} –0.5	V_{REF} +0.5	V_{REF}	0.90
SSTL3 I & II	V_{REF} –1.0	V_{REF} +1.0	V_{REF}	1.5
SSTL2 I & II	V_{REF} –0.75	V_{REF} +0.75	V_{REF}	1.25
CTT	V_{REF} –0.2	V_{REF} +0.2	V_{REF}	1.5
AGP	V_{REF} – (0.2xV_{CCO})	V_{REF} + (0.2xV_{CCO})	V_{REF}	Per AGP Spec
LVDS	1.2 –0.125	1.2 + 0.125	1.2	
LVPECL	1.6 –0.3	1.6 + 0.3	1.6	

Notes:
1. Input waveform switches between V_L and V_H.
2. Measurements are made at V_{REF} (Typ), Maximum, and Minimum. Worst-case values are reported.

   I/O parameter measurements are made with the capacitance values shown in Table 3. See the application examples (in Module 2 of this data sheet) for appropriate terminations.

   I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Low Voltage Differential Signals

The Virtex-E family incorporates low-voltage signalling (LVDS and LVPECL). Two pins are utilized for these signals to be connected to a Virtex-E device. These are known as differential pin pairs. Each differential pin pair has a Positive (P) and a Negative (N) pin. These pairs are labeled in the following manner.

IO_L#[P/N]

where

L = LVDS or LVPECL pin
# = Pin Pair Number
P = Positive
N = Negative

I/O pins for differential signals can either be synchronous or asynchronous, input or output. The pin pairs can be used for synchronous input and output signals as well as asynchronous input signals. However, only some of the low-voltage pairs can be used for asynchronous output signals.

DIfferential signals require the pins of a pair to switch almost simultaneously. If the signals driving the pins are from IOB flip-flops, they are synchronous. If the signals driving the pins are from internal logic, they are asynchronous. Table 2 defines the names and function of the different types of low-voltage pin pairs in the Virtex-E family.

Table 2: **LVDS Pin Pairs**

Pin Name	Description
IO_L#[P/N] Example: IO_L22N	Represents a general IO or a synchronous input/output differential signal. When used as a differential signal, N means Negative I/O and P means Positive I/O.
IO_L#[P/N]_Y Example: IO_L22N_Y	Represents a general IO or a synchronous input/output differential signal, or a part-dependent asynchronous output differential signal.
IO_L#[P/N]_YY Example: O_L22N_YY	Represents a general IO or a synchronous input/output differential signal, or an asynchronous output differential signal.
IO_LVDS_DLL_L#[P/N] Example: IO_LVDS_DLL_L16N	Represents a general IO or a synchronous input/output differential signal, a differential clock input signal, or a DLL input. When used as a differential clock input, this pin is paired with the adjacent GCK pin. The GCK pin is always the positive input in the differential clock input configuration.

Virtex-E Package Pinouts

The Virtex-E family of FPGAs is available in 12 popular packages, including chip-scale, plastic and high heat-dissipation quad flat packs, and ball grid and fine-pitch ball grid arrays. Family members have footprint compatibility across devices provided in the same package. The pinout tables in this section indicate function, pin, and bank information for each package/device combination. Following each pinout table is an additional table summarizing information specific to differential pin pairs for all devices provided in that package.

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
2	IO_D3_L30N _Y	M3
2	IO_L31P	M2
2	IO_L31N	M1
2	IO	N3[1]
2	IO_L32P_YY	N4
2	IO_L32N_YY	N2
3	IO	P1
3	IO	P3[1]
3	IO_L33P	R1
3	IO_L33N	R2
3	IO_D4_L34P _Y	R3
3	IO_VREF_3_L34N _Y	R4
3	IO_L35P_YY	T2
3	IO_L35N_YY	U2
3	IO	T3[1]
3	IO_L36P	T4
3	IO_L36N	V1
3	IO	V2[1]
3	IO_L37P_YY	U3
3	IO_D5_L37N_YY	U4
3	IO_D6_L38P _Y	V3
3	IO_VREF_3_L38N _Y	V4
3	IO_L39P _Y	Y1
3	IO_L39N _Y	Y2
3	IO	W3
3	IO	W4[1]
3	IO	AA1[1]
3	IO_L40P_Y	AA2
3	IO_VREF_3_L40N_Y	Y3
3	IO_L41P_YY	AC1
3	IO_L41N_YY	AB2
3	IO	AA3[1]
3	IO_L42P_YY	AA4

Table 10: **BG352 — XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
3	IO_VREF_3_L42N_YY	AC2[2]
3	IO	AB3
3	IO	AD1[1]
3	IO	AB4[1]
3	IO_D7_L43P_YY	AC3
3	IO_INIT_L43N_YY	AD2
4	IO_L44P_YY	AC5
4	IO_L44N_YY	AD4
4	IO	AE3[1]
4	IO	AD5[1]
4	IO	AC6
4	IO_VREF_4_L45P_YY	AE4[2]
4	IO_L45N_YY	AF3
4	IO	AF4[1]
4	IO_L46P_YY	AC7
4	IO_L46N_YY	AD6
4	IO_VREF_4_L47P_YY	AE5
4	IO_L47N_YY	AE6
4	IO	AD7[1]
4	IO	AE7[1]
4	IO_L48P	AF6
4	IO_L48N	AC9
4	IO	AD8
4	IO_VREF_4_L49P_YY	AE8
4	IO_L49N_YY	AF7
4	IO_L50P_YY	AD9
4	IO_L50N_YY	AE9
4	IO	AD10[1]
4	IO_L51P	AF9
4	IO_L51N	AC11
4	IO	AE10[1]
4	IO_L52P_Y	AD11
4	IO_L52N_Y	AE11

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
6	VCCO	AL31
7	VCCO	A31
7	VCCO	L28
7	VCCO	L31
NA	GND	A2
NA	GND	A3
NA	GND	A7
NA	GND	A9
NA	GND	A14
NA	GND	A18
NA	GND	A23
NA	GND	A25
NA	GND	A29
NA	GND	A30
NA	GND	B1
NA	GND	B2
NA	GND	B30
NA	GND	B31
NA	GND	C1
NA	GND	C31
NA	GND	D16
NA	GND	G1
NA	GND	G31
NA	GND	J1
NA	GND	J31
NA	GND	P1
NA	GND	P31
NA	GND	T4
NA	GND	T28
NA	GND	V1
NA	GND	V31
NA	GND	AC1
NA	GND	AC31
NA	GND	AE1
NA	GND	AE31

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	AH16
NA	GND	AJ1
NA	GND	AJ31
NA	GND	AK1
NA	GND	AK2
NA	GND	AK30
NA	GND	AK31
NA	GND	AL2
NA	GND	AL3
NA	GND	AL7
NA	GND	AL9
NA	GND	AL14
NA	GND	AL18
NA	GND	AL23
NA	GND	AL25
NA	GND	AL29
NA	GND	AL30

Notes:

1. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV400E, XCV600E; otherwise, I/O option only.

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
3	IO_L50N_YY	P19
3	IO_L51P_YY	P18
3	IO_D5_L51N_YY	R21
3	IO_D6_L52P_Y	T22
3	IO_VREF_L52N_Y	R19
3	IO_L53P_Y	U22
3	IO_L53N_Y	R18
3	IO_L54P_YY	T21
3	IO_L54N_YY	V22
3	IO_L55P_YY	T20
3	IO_VREF_L55N_YY	U21
3	IO_L56P_YY	W22
3	IO_L56N_YY	T18
3	IO_L57P_YY	U19
3	IO_VREF_L57N_YY	U20
3	IO_L58P_YY	W21
3	IO_L58N_YY	AA22
3	IO_D7_L59P_YY	Y21
3	IO_INIT_L59N_YY	V19
3	IO	M22
4	GCK0	W12
4	IO	W14
4	IO	Y13
4	IO	Y17
4	IO	AA16[1]
4	IO	AA19
4	IO	AB12[1]
4	IO	AB17
4	IO	AB21[1]
4	IO_L60P_YY	W18
4	IO_L60N_YY	AA20
4	IO_L61P	Y18
4	IO_L61N	V17
4	IO_VREF_L62P_YY	AB20
4	IO_L62N_YY	W17
4	IO_L63P	AA18

Table 18: **FG456 — XCV200E and XCV300E**

Bank	Pin Description	Pin #
4	IO_L63N	V16
4	IO_VREF_L64P_YY	AB19
4	IO_L64N_YY	AB18
4	IO_L65P_Y	W16
4	IO_L65N_Y	AA17
4	IO_L66P_Y	Y16
4	IO_L66N_Y	V15
4	IO_VREF_L67P_YY	AB16
4	IO_L67N_YY	Y15
4	IO_L68P_YY	AA15
4	IO_L68N_YY	AB15
4	IO_L69P_Y	W15
4	IO_L69N_Y	Y14
4	IO_L70P_Y	V14
4	IO_L70N_Y	AA14
4	IO_L71P	AB14
4	IO_L71N	V13
4	IO_VREF_L72P_YY	AA13
4	IO_L72N_YY	AB13
4	IO_L73P_Y	W13
4	IO_L73N_Y	AA12
4	IO_L74P_Y	Y12
4	IO_L74N_Y	V12
4	IO_LVDS_DLL_L75P	U12
5	IO	U11[1]
5	IO	V8
5	IO	W5
5	IO	AA3[1]
5	IO	AA9
5	IO	AA10
5	IO	AB4
5	IO	AB7[1]
5	IO	AB8
5	GCK1	Y11
5	IO_LVDS_DLL_L75N	AA11
5	IO_L76P_Y	AB11

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	IO_L9N	A7
0	IO_L9P	D9
0	IO_L10N	B8
0	IO_VREF_L10P	G10
0	IO_L11N_YY	C9
0	IO_L11P_YY	F10
0	IO_L12N_Y	A8
0	IO_L12P_Y	E10
0	IO_L13N_YY	G11
0	IO_L13P_YY	D10
0	IO_L14N_YY	B10
0	IO_L14P_YY	F11
0	IO_L15N	C10
0	IO_L15P	E11
0	IO_L16N_YY	G12
0	IO_L16P_YY	D11
0	IO_VREF_L17N_YY	C11
0	IO_L17P_YY	F12
0	IO_L18N_YY	A11
0	IO_L18P_YY	E12
0	IO_L19N_Y	D12
0	IO_L19P_Y	C12
0	IO_VREF_L20N_Y	A12
0	IO_L20P_Y	H13
0	IO_LVDS_DLL_L21N	B13
1	GCK2	C13
1	IO	A13[1]
1	IO	A16[1]
1	IO	A19
1	IO	A20
1	IO	A22
1	IO	A24[1]
1	IO	B15[1]
1	IO	B17[1]
1	IO	B23
1	IO_LVDS_DLL_L21P	F14

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
1	IO_L22N	E14
1	IO_L22P	F13
1	IO_L23N_Y	D14
1	IO_VREF_L23P_Y	A14
1	IO_L24N_Y	C14
1	IO_L24P_Y	H14
1	IO_L25N_YY	G14
1	IO_L25P_YY	C15
1	IO_L26N_YY	E15
1	IO_VREF_L26P_YY	D15
1	IO_L27N_YY	C16
1	IO_L27P_YY	F15
1	IO_L28N	G15
1	IO_L28P	D16
1	IO_L29N_YY	E16
1	IO_L29P_YY	A17
1	IO_L30N_YY	C17
1	IO_L30P_YY	E17
1	IO_L31N_Y	F16
1	IO_L31P_Y	D17
1	IO_L32N_YY	F17
1	IO_L32P_YY	C18
1	IO_L33N_YY	A18
1	IO_VREF_L33P_YY	G16
1	IO_L34N_YY	C19
1	IO_L34P_YY	G17
1	IO_L35N_Y	D18
1	IO_VREF_L35P_Y	B19[2]
1	IO_L36N_Y	D19
1	IO_L36P_Y	E18
1	IO_L37N_YY	F18
1	IO_L37P_YY	B20
1	IO_L38N_YY	G19
1	IO_VREF_L38P_YY	C20
1	IO_L39N_YY	G18
1	IO_L39P_YY	E19
1	IO_L40N_YY	A21

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	NC	L2
NA	NC	F6
NA	NC	F25
NA	NC	F21
NA	NC	F2
NA	NC	C26
NA	NC	C25
NA	NC	C2
NA	NC	C1
NA	NC	B6
NA	NC	B26
NA	NC	B24
NA	NC	B21
NA	NC	B16
NA	NC	B11
NA	NC	B1
NA	NC	AF25
NA	NC	AF24
NA	NC	AF2
NA	NC	AE6
NA	NC	AE3
NA	NC	AE26
NA	NC	AE24
NA	NC	AE21
NA	NC	AE16
NA	NC	AE14
NA	NC	AE11
NA	NC	AE1
NA	NC	AD25
NA	NC	AD2
NA	NC	AD1
NA	NC	AA6
NA	NC	AA25
NA	NC	AA21
NA	NC	AA2
NA	NC	A3
NA	NC	A25

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	NC	A2
NA	NC	A15
NA	VCCINT	G7
NA	VCCINT	G20
NA	VCCINT	H8
NA	VCCINT	H19
NA	VCCINT	J9
NA	VCCINT	J10
NA	VCCINT	J11
NA	VCCINT	J16
NA	VCCINT	J17
NA	VCCINT	J18
NA	VCCINT	K9
NA	VCCINT	K18
NA	VCCINT	L9
NA	VCCINT	L18
NA	VCCINT	T9
NA	VCCINT	T18
NA	VCCINT	U9
NA	VCCINT	U18
NA	VCCINT	V9
NA	VCCINT	V10
NA	VCCINT	V11
NA	VCCINT	V16
NA	VCCINT	V17
NA	VCCINT	V18
NA	VCCINT	Y7
NA	VCCINT	Y20
NA	VCCINT	W8
NA	VCCINT	W19
0	VCCO	J13
0	VCCO	J12
0	VCCO	H9
0	VCCO	H12
0	VCCO	H11

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
2	IO	D29[5]
2	IO	G26[4]
2	IO	H24[4]
2	IO	H25[4]
2	IO	H28[5]
2	IO	J25[4]
2	IO	J27[5]
2	IO	K30[4]
2	IO	M24[4]
2	IO	M25[4]
2	IO	N20
2	IO	N23[4]
2	IO	P26[5]
2	IO	P27[5]
2	IO	P30[4]
2	IO	R30
2	IO_DOUT_BUSY_L70P_YY	J22
2	IO_DIN_D0_L70N_YY	E27
2	IO_L71P	C29[4]
2	IO_L71N	D28[3]
2	IO_L72P_Y	G25
2	IO_L72N_Y	E25
2	IO_VREF_L73P_YY	E28[1]
2	IO_L73N_YY	C30
2	IO_L74P_Y	K22[4]
2	IO_L74N_Y	F27[3]
2	IO_L75P_YY	D30
2	IO_L75N_YY	J23
2	IO_VREF_L76P_Y	L21
2	IO_L76N_Y	F28
2	IO_L77P_YY	G28
2	IO_L77N_YY	E30
2	IO_L78P_YY	G27
2	IO_L78N_YY	E29
2	IO_L79P	K23
2	IO_L79N	H26
2	IO_VREF_L80P_YY	F30

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
2	IO_L80N_YY	L22
2	IO_L81P_YY	H27
2	IO_L81N_YY	G29
2	IO_L82P	G30
2	IO_L82N	M21
2	IO_L83P_YY	J24
2	IO_L83N_YY	J26
2	IO_VREF_L84P_YY	H30
2	IO_L84N_YY	L23
2	IO_L85P_YY	K26[4]
2	IO_L85N_YY	J28[3]
2	IO_L86P_YY	J29
2	IO_L86N_YY	K24
2	IO_L87P_YY	K27[4]
2	IO_VREF_L87N_YY	J30
2	IO_D1_L88P	M22
2	IO_D2_L88N	K29
2	IO_L89P_YY	K28[3]
2	IO_L89N_YY	L25[4]
2	IO_L90P	N21
2	IO_L90N	K25
2	IO_L91P_YY	L24
2	IO_L91N_YY	L27
2	IO_L92P_Y	L29[4]
2	IO_L92N_Y	M23[4]
2	IO_L93P_YY	L26
2	IO_L93N_YY	L28
2	IO_VREF_L94P	L30[1]
2	IO_L94N	M27
2	IO_L95P_YY	M26
2	IO_L95N_YY	M29
2	IO_L96P_YY	N29
2	IO_L96N_YY	M30
2	IO_L97P	N25
2	IO_L97N	N27
2	IO_VREF_L98P_YY	N30
2	IO_D3_L98N_YY	P21

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
2	IO_L99P_YY	N26
2	IO_L99N_YY	P28
2	IO_L100P	P29
2	IO_L100N	N24
2	IO_L101P_YY	P22
2	IO_L101N_YY	R26
2	IO_VREF_L102P_YY	P25
2	IO_L102N_YY	R29
2	IO_L103P_YY	R21[4]
2	IO_L103N_YY	R28[3]
2	IO_VREF_L104P_YY	R25[2]
2	IO_L104N_YY	T30
2	IO_L105P_YY	P24[4]
2	IO_L105N_YY	R27[3]
2	IO_L106P	R24
3	IO	T22[4]
3	IO	T24[4]
3	IO	T26[4]
3	IO	T29[4]
3	IO	U26[5]
3	IO	V23[4]
3	IO	V25[4]
3	IO	V30[5]
3	IO	Y21[4]
3	IO	AA26[4]
3	IO	AA23[4]
3	IO	AB27[4]
3	IO	AB29[4]
3	IO	AC28[5]
3	IO	AD26[4]
3	IO	AD29[5]
3	IO	AE27[5]
3	IO_L106N	U29
3	IO_L107P_YY	R22
3	IO_VREF_L107N_YY	T27[2]
3	IO_L108P_YY	R23

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
3	IO_L108N_YY	T28
3	IO_L109P_YY	T21
3	IO_VREF_L109N_YY	T25
3	IO_L110P_YY	U28
3	IO_L110N_YY	U30
3	IO_L111P	T23
3	IO_L111N	U27
3	IO_L112P_YY	U25
3	IO_L112N_YY	V27
3	IO_D4_L113P_YY	U24
3	IO_VREF_L113N_YY	V29
3	IO_L114P	W30
3	IO_L114N	U22
3	IO_L115P_YY	U21
3	IO_L115N_YY	W29
3	IO_L116P_YY	V26
3	IO_L116N_YY	W27
3	IO_L117P	W26
3	IO_VREF_L117N	Y29[1]
3	IO_L118P_YY	W25
3	IO_L118N_YY	Y30
3	IO_L119P_Y	V24[4]
3	IO_L119N_Y	Y28[4]
3	IO_L120P_YY	AA30
3	IO_L120N_YY	W24
3	IO_L121P	AA29
3	IO_L121N	V20
3	IO_L122P	Y27[4]
3	IO_L122N	W23[4]
3	IO_L123P_YY	Y26
3	IO_D5_L123N_YY	AB30
3	IO_D6_L124P_YY	V21
3	IO_VREF_L124N_YY	AA28
3	IO_L125P_YY	Y25
3	IO_L125N_YY	AA27
3	IO_L126P_YY	W22
3	IO_L126N_YY	Y23

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
5	IO_L182N	AF13
5	IO_L183P	AH14
5	IO_L183N	AJ14
5	IO_L184P_YY	AE14
5	IO_VREF_L184N_YY	AG13
5	IO_L185P_YY	AK13
5	IO_L185N_YY	AD13
5	IO_L186P	AE13
5	IO_L186N	AF12
5	IO_L187P	AC13
5	IO_L187N	AA13
5	IO_L188P_YY	AA12
5	IO_VREF_L188N_YY	AJ12[1]
5	IO_L189P_YY	AB12
5	IO_L189N_YY	AE11
5	IO_L190P	AK12[4]
5	IO_L190N	Y13[4]
5	IO_L191P	AG11
5	IO_L191N	AF11
5	IO_L192P	AH11
5	IO_L192N	AJ11
5	IO_L193P_YY	AE12[4]
5	IO_L193N_YY	AG10[4]
5	IO_L194P_YY	AD12
5	IO_L194N_YY	AK11
5	IO_L195P_YY	AJ10
5	IO_VREF_L195N_YY	AC12
5	IO_L196P_YY	AK10
5	IO_L196N_YY	AD11
5	IO_L197P_YY	AJ9
5	IO_L197N_YY	AE9
5	IO_L198P_YY	AH10
5	IO_VREF_L198N_YY	AF9
5	IO_L199P_YY	AH9
5	IO_L199N_YY	AK9
5	IO_L200P	AF8
5	IO_L200N	AB11

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
5	IO_L201P	AC11
5	IO_L201N	AG8
5	IO_L202P_YY	AK8
5	IO_VREF_L202N_YY	AF7
5	IO_L203P_YY	AG7
5	IO_L203N_YY	AK7
5	IO_L204P	AJ7
5	IO_L204N	AD10
5	IO_L205P	AH6
5	IO_L205N	AC10
5	IO_L206P_YY	AD9
5	IO_VREF_L206N_YY	AG6
5	IO_L207P_YY	AB10
5	IO_L207N_YY	AJ5
5	IO_L208P	AD8[4]
5	IO_L208N	AK5[4]
5	IO_L209P	AC9
5	IO_VREF_L209N	AJ4[1]
5	IO_L210P	AG5
5	IO_L210N	AK4
5	IO_L211P_YY	AH5[3]
5	IO_L211N_YY	AG3[4]
6	IO	T2[4]
6	IO	T10[4]
6	IO	U1
6	IO	U4[5]
6	IO	U6[4]
6	IO	U7[4]
6	IO	V1[4]
6	IO	V5[5]
6	IO	V8
6	IO	Y10[4]
6	IO	AA4[4]
6	IO	AB5[5]
6	IO	AB7[4]
6	IO	AC3[5]

FG900 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
GCLK LVDS					
3	0	C15	A15	NA	IO_DLL_ 34N
2	1	E15	E16	NA	IO_DLL_ 34P
1	5	AK16	AH16	NA	IO_DLL_ 177N
0	4	AJ16	AF16	NA	IO_DLL_ 177P
IO LVDS Total Pairs: 283, Asynchronous Output Pairs: 168					
0	0	F7	C4	4	-
1	0	G8	D5	2	-
2	0	H9	A3	2	VREF
3	0	J10	B4	2	-
4	0	D6	A4	√	-
5	0	B5	E7	√	VREF
6	0	F8	A5	1	-
7	0	N11	D7	1	-
8	0	E8	G9	√	-
9	0	J11	A6	√	VREF
10	0	B7	C7	2	-
11	0	H10	C8	2	-
12	0	F10	G10	√	-
13	0	H11	A8	√	VREF
14	0	C9	D9	NA	-
15	0	J12	B9	4	-
16	0	A9	E10	NA	VREF
17	0	B10	G11	NA	-

Table 27: **FG900 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	0	C10	H12	4	-
19	0	F11	H13	2	-
20	0	D11	E11	2	-
21	0	G12	B11	2	-
22	0	C11	F12	√	-
23	0	D12	A10	√	VREF
24	0	A11	E12	1	-
25	0	B12	G13	1	-
26	0	K13	A12	√	-
27	0	B13	F13	√	VREF
28	0	E13	G14	2	-
29	0	B14	D14	2	-
30	0	J14	A14	√	-
31	0	J15	K14	√	VREF
32	0	H15	B15	NA	-
33	0	D15	F15	√	VREF
34	1	E16	A15	NA	IO_ LVDS_DLL
35	1	F16	B16	4	VREF
36	1	H16	A16	4	-
37	1	K15	C16	√	VREF
38	1	G16	K16	√	-
39	1	E17	A17	2	-
40	1	C17	F17	2	-
41	1	A18	E18	√	VREF
42	1	A19	D18	√	-
43	1	G18	B19	1	-
44	1	H18	D19	1	-
45	1	F19	F18	√	VREF
46	1	K17	B20	√	-
47	1	A20	D20	2	-
48	1	C20	G19	2	-
49	1	E20	K18	2	-
50	1	D21	B21	4	-
51	1	A21	F20	√	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
71	1	A27	G24	3200 2000 1000	-
72	1	G25	B27	3200 1600	-
73	1	C27	E26	3200 2600 2000 1600 1000	VREF
74	1	B28	J24	3200 2600 2000 1600 1000	-
75	1	H25	K24	3200 2600	-
76	1	F26	D27	3200 1000	-
77	1	C28	G26	3200 1000	-
78	1	J25	E27	2000 1600	-
79	1	H26	A30	3200 2600 2000 1600 1000	VREF
80	1	B29	G27	3200 2600 2000 1600 1000	-
81	1	C29	F27	3200 2600 1000	-
82	1	F28	E28	3200 2000 1000	VREF
83	1	B30	L25	3200 2000 1000	-
84	1	E29	B31	3200 1600 1000	-
85	1	D30	A31	3200 2600 2000 1600 1000	CS
86	2	D32	J27	3200 2600 2000 1600 1000	DIN, D0
87	2	E31	F30	3200 2600 2000	-
88	2	G29	F32	2600 2000 1000	-
89	2	E32	G30	3200 2600 1600 1000	VREF
90	2	M25	G31	2600 1600	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
91	2	L26	D33	3200 2600 1600 1000	-
92	2	D34	H29	2600 2000 1000	VREF
93	2	J28	E33	3200 2600 2000 1600	-
94	2	H28	H30	3200 2600 2000 1600 1000	-
95	2	H32	K28	3200 2600 1600 1000	-
96	2	L27	F33	3200 2600 2000	-
97	2	M26	E34	2600 2000 1000	-
98	2	H31	G32	3200 2600 2000 1600 1000	VREF
99	2	N25	J31	2000 1600	-
100	2	J30	G33	3200 2600 2000 1600 1000	-
101	2	H34	J29	2600 1000	VREF
102	2	M27	H33	3200 2600 1600	-
103	2	K29	J34	3200 2600 1600 1000	-
104	2	L29	J33	3200 2600 2000 1600 1000	VREF
105	2	M28	K34	3200 2600 2000 1600 1000	-
106	2	N27	L34	3200 1600 1000	-
107	2	K33	P26	2000 1600 1000	D1
108	2	R25	M34	3200 2600 2000	-
109	2	L31	L33	2000 1000	-
110	2	P27	M33	3200 2600 1600 1000	-

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
153	3	AD31	AF33	3200 2600 2000 1600 1000	VREF
154	3	AC28	AF31	3200 2600 1600 1000	-
155	3	AC27	AF32	3200 2600 1600	-
156	3	AE29	AD28	2600 1000	VREF
157	3	AD30	AG32	3200 2600 2000 1600 1000	-
158	3	AC26	AH33	2000 1600	-
159	3	AD26	AF30	3200 2600 2000 1600 1000	VREF
160	3	AC25	AH32	2600 2000 1000	-
161	3	AE28	AL34	3200 2600 2000	-
162	3	AG30	AD27	3200 2600 1600 1000	-
163	3	AF29	AK34	3200 2600 2000 1600 1000	-
164	3	AD25	AE27	3200 2600 2000 1600	-
165	3	AJ33	AH31	2600 2000 1000	VREF
166	3	AE26	AL33	3200 2600 1600 1000	-
167	3	AF28	AL32	2600 1600	-
168	3	AJ31	AF27	3200 2600 1600 1000	VREF
169	3	AG29	AJ32	2600 2000 1000	-
170	3	AK33	AH30	3200 2600 2000	-
171	3	AK32	AK31	3200 2600 2000 1600 1000	INIT

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
172	4	AP31	AK29	3200 2600 2000 1600 1000	-
173	4	AP30	AN31	3200 1600 1000	-
174	4	AH27	AN30	3200 2000 1000	-
175	4	AM30	AK28	3200 2000 1000	VREF
176	4	AG26	AN29	3200 2600 1000	-
177	4	AF25	AM29	3200 2600 2000 1600 1000	-
178	4	AL29	AL28	3200 2600 2000 1600 1000	VREF
179	4	AE24	AN28	2000 1600	-
180	4	AJ27	AH26	3200 1000	-
181	4	AG25	AK27	3200 1000	-
182	4	AM28	AF24	3200 2600	-
183	4	AJ26	AP27	3200 2600 2000 1600 1000	-
184	4	AK26	AN27	3200 2600 2000 1600 1000	VREF
185	4	AE23	AM27	3200 1600	-
186	4	AL26	AP26	3200 2000 1000	-
187	4	AN26	AJ25	3200 2000 1000	VREF
188	4	AG24	AP25	3200 2600	-
189	4	AF23	AM26	3200 2600 2000 1600 1000	-
190	4	AJ24	AN25	3200 2600 2000 1600 1000	VREF
191	4	AE22	AM25	2600 1600 1000	-

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “V_{REF} or I/O option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.
11/20/00	1.8	• Upgraded speed grade -8 numbers in **Virtex-E Electrical Characteristics** tables to Preliminary. • Updated minimums in Table 13 and added notes to Table 14. • Added to note 2 to **Absolute Maximum Ratings**. • Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF}. • Changed all minimum hold times to –0.4 under **Global Clock Set-Up and Hold for LVTTL Standard, with DLL**. • Revised maximum T_{DLLPW} in -6 speed grade for **DLL Timing Parameters**. • Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	• Revised footnote for Table 14. • Added numbers to **Virtex-E Electrical Characteristics** tables for XCV1000E and XCV2000E devices. • Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. • Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. • Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.